Claim Amendments

Please amend the claims as follows.

Claims 1-16 (canceled)

17. (original) A surface acoustic wave (SAW) device sealed at the wafer level, the device comprising:

an active area to be protected;

an electrical contact area; and

a lithographically-formed structure sealing at least the active area and leaving at least a portion of the electrical contact area exposed.

18. (original) The device of claim 17, wherein the lithographically-formed structure comprises a glassy material.

19. (original) The device of claim 17, wherein the SAW device is fabricated on a substrate from a group of substrates consisting of lithium tantalate, lithium niobate, and quartz.

20. (original) A lithographically-fabricated surface acoustic wave (SAW) device, the SAW device comprising:

means for carrying a surface acoustic wave; and

a wafer-level means for sealing the means for carrying the surface acoustic wave.

21. (new) The SAW device of claim 20, wherein the means for carrying the surface acoustic wave comprises a transducer structure.

22. (new) The SAW device of claim 21, wherein the transducer structure comprises aluminum pattered into interdigitated electrode fingers.

23. (new) The SAW device of claim 20, wherein the wafer-level means for sealing comprises a lithographically-formed structure sealing at least the means for carrying.

24. (new) The SAW device of claim 23, further comprising electrical contact areas coupled to the means for carrying, and wherein the wafer-level means for sealing leaves exposed at least a portion of the electrical contact areas.

25. (new) The device of claim 17, wherein the lithographically-formed structure comprises a material of a thickness so as to be impermeable to undesired contaminants.

26. (new) The device of claim 17, wherein the lithographically-formed structure comprises silicon dioxide.

27. (new) The device of claim 17, wherein the lithographically-formed structure comprises silicon nitride.

28. (new) The device of claim 17, wherein the lithographically-formed structure comprises a metal.

29. (new) The device of claim 18, wherein the glassy material comprises a spin-on-glass.

30. (new) The device of claim 18, wherein the glassy material comprises a sputtered glass.

31. (new) The device of claim 17, wherein the SAW device is fabricated on a lithium tantalate substrate.

32. (new) The device of claim 17, wherein the SAW device is fabricated on a lithium niobate substrate.

33. (new) The device of claim 17, wherein the SAW device is fabricated on a quartz substrate.